Special Issue

Applied Seismology - Identification of Aftershocks

Message from the Guest Editors

The identification of aftershocks triggered after a major earthquake in earthquake catalogs is the main aim of this Special Issue. Contributions dealing with the identification approaches, based on the analysis of spatiotemporal properties, statistical analysis and modeling, empirical methods, and quantitative analyses are encouraged. The aftershock duration, their spatial extent, and their energetic properties, in connection with the physical properties and state of stress, are characteristics worth inclusion in the submitted papers. The evolution of the aftershock sequences, the identification of secondary aftershocks, subsequences into a major sequence, and possible relation with fluid migration are also of importance.Assistant George Kaviris

Guest Editors

Dr. George Kaviris

Prof. Dr. Vasilios Karakostas

Prof. Dr. Zuniga Ramon

Deadline for manuscript submissions

closed (31 December 2021)

Applied Sciences

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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